



100% Material Declaration Data Sheet FG860

PK157 (v1.2) September 25, 2006

Material Declaration Data Sheet

Average Weight: 10.904 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.1201	1.10%
	Silicon	7440-21-3	100.00		0.1201	
Die Attach Material					0.012	0.11%
	Silver	7440-22-4	75.00		0.009	
	Resin	Trade Secret	25.00		0.003	
Mold Compound					0.4135	7.31%
	Epoxy Resins	Trade Secret	26.00		0.207	
	SiO2	60676-86-0	74.00	Filler	0.590	
Laminate					0.7897	7.24%
	Laminate	Trade Secret			0.481	
	Solder Mask	Trade Secret			0.168	
	Copper	7440-50-8		Metal Layer	0.122	
	Nickel	7440-02-0		Metal Layer	0.014	
	Gold	7440-57-5		Metal Layer	0.005	
Heat Sink					7.0645	64.79%
	Copper	7440-50-8	97.50		6.888	
	Iron	7439-89-6	2.35		0.166	
	Phosphorus	7723-14-0	0.003		0.0002	
	Zinc	7440-66-6	0.12		0.008	
Heat Snk Plating					0.3292	3.02%
	Nickel	7440-05-0	100.00		0.3292	
Dam					0.0148	0.13%
	Epoxy Resin	Trade Secret	100.00		0.0148	
Bond Wire					0.0236	0.22%
	Gold	7440-57-5	100.00		0.0236	
Solder Balls					1.752	16.07%
	Tin	7440-31-5	63.00		1.104	
	Lead	7439-92-1	37.00		0.648	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/27/06	1.0	Initial release.
6/15/06	1.1	100% Material Declaration.
9/25/06	1.2	Update component descriptions.